

Full Material Declaration for attached parts list

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Diotec Semiconductor AG

DUNS number: 330866844

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Declarations authorised by:

Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 May 2009 [Approved on 31 July 2026, 13:16 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.08%	ALUMINIUM	7429-90-5	0.1%
			Nickel	7440-02-0	0.4%
			REACH Article 67 Exemption		
			Silver	7440-22-4	28.6%
			Silicon	7440-21-3	70.9%
Encapsulation	Glass	30.02%	Aluminium oxide	1344-28-1	2%
			Sodium oxide (Na ₂ O)	1313-59-3	3%
			Lithium oxide (Li ₂ O)	12057-24-8	4%
			Rutile (TiO ₂)	1317-80-2	4%
			ZINCITE (MINERAL)	1314-13-2	4%
			Potassium oxide (K ₂ O)	12136-45-7	7.5%
			BORON TRIOXIDE	1303-86-2	20%
			Silicon Dioxide	7631-86-9	55.5%
Leadfinish	Tin plating	0.13%	Tin	7440-31-5	100%
Leadframe	Copper alloys	69.77%	COPPER, ELEMENTAL	7440-50-8	24%
			Iron	7439-89-6	34%
			Nickel	7440-02-0	42%
			REACH Article 67 Exemption		

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-8oC/Glass MiniMELF_HF	SOD-8oC/Glass MiniMELF_HF	0.04	g